

Express Mail Label No. _____

Dated: _____

Docket No.: 20099/0200781-US0
(PATENT)



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Ken Koyama et al.

Application No.: 10/781,358

Confirmation No.: 9212

Filed: February 17, 2004

Art Unit: 1775

For: Al-Cu BONDED STRUCTURE AND METHOD
FOR MAKING THE SAME

Examiner: John J. Zimmerman

**DISCLAIMING DECLARATION OF
SHIZUO MASUMOTO UNDER 37 C.F.R. § 1.132**

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir :

I, Shizuo MASUMOTO, do hereby declare and state as follows:

1. I am a citizen of Japan and am more than twenty-one years of age.

2. Ken Koyama, Keiji Miki, Atsushi Mochida, Kenji Ikeda, Makoto Yoshida, and Kenji Shinozaki, and myself are co-authors of the article entitled "Improvement of Strength of Brazing Joint using Ag as Insert Metal - Development of Brazing Technique for Al-Cu Dissimilar Joint (Part 2)," *Light Metal Soldering*, Vol. 41 (2003) No. 2, pages 29-82 (hereinafter "Article"). Upon information and belief, this article was published on February 16, 2003, *i.e.*, less than one year prior to the international filing date (August 13, 2003) of the PCT application. The present application is a national stage of the PCT application indicated above.

3. I have read and am familiar with the instant application filed in the U.S. Patent and Trademark Office (the "USPTO"), and the pending claims of the application.

4. I understand that the publication listed in ¶2 (Article.) would possibly be relied upon in a future Office Action to reject claims of the application under 35 U.S.C. § 102(a). The present declaration is submitted to describe my contribution as one of the authors of the publication listed in ¶2.

5. As one of co-authors, I did not provide any inventive contribution towards the matter commonly described in the Article and the present application. I was involved towards technical support in my official capacity and did not provide any intellectual input into the project on which the invention of the present application is based.

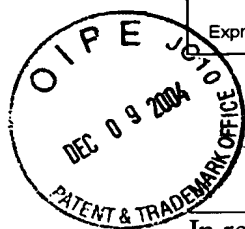
6. The Al-Cu bonded structure and method for making the structure described in the Article., was the invention of Ken Koyama, Keiji Miki, Makoto Yoshida, and Kenji Shinozaki, and I did not, therefore contribute to the conception of any of the presently claimed subject matter of the instant application.

7. I further declare that all statements herein of my knowledge are true and that all statements made on information and belief are believed to be true; and further that willful false statements and the like so made are punishable by fine or imprisonment, or both, under §1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the present application or any patent issuing thereon.

Dated: December 3, 2004

Shizuo Masumoto

Shizuo Masumoto



Express Mail Label No. _____

Dated: _____

Docket No.: 20099/0200781-USO
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Ken Koyama et al.

Application No.: 10/781,358

Confirmation No.: 9212

Filed: February 17, 2004

Art Unit: 1775

For: Al-Cu BONDED STRUCTURE AND METHOD
FOR MAKING THE SAME

Examiner: John J. Zimmerman

**DISCLAIMING DECLARATION OF
ATSUSHI MOCHIDA UNDER 37 C.F.R. § 1.132**

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

I, Atsushi MOCHIDA, do hereby declare and state as follows:

1. I am a citizen of Japan and am more than twenty-one years of age.
2. Ken Koyama, Keiji Miki, Atsushi Mochida, Kenji Ikeda, Makoto Yoshida, and Kenji Shinozaki, and myself are co-authors of the article entitled "Improvement of Strength of Brazing Joint using Ag as Insert Metal - Development of Brazing Technique for Al-Cu Dissimilar Joint (Part 2)," *Light Metal Soldering*, Vol. 41 (2003) No. 2, pages 29-82 (hereinafter "Article"). Upon information and belief, this article was published on February 16, 2003, *i.e.*, less than one year prior to the international filing date (August 13, 2003) of the PCT application. The present application is a national stage of the PCT application indicated above.
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5. As one of co-authors, I did not provide any inventive contribution towards the matter commonly described in the Article and the present application. I was involved towards technical support in my official capacity and did not provide any intellectual input into the project on which the invention of the present application is based.

6. The Al-Cu bonded structure and method for making the structure described in the Article, was the invention of Ken Koyama, Keiji Miki, Makoto Yoshida, and Kenji Shinozaki, and I did not, therefore contribute to the conception of any of the presently claimed subject matter of the instant application.

7. I further declare that all statements herein of my knowledge are true and that all statements made on information and belief are believed to be true; and further that willful false statements and the like so made are punishable by fine or imprisonment, or both, under §1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the present application or any patent issuing thereon.

Dated: December 6, 2004

Atsushi Mochida

Atsushi Mochida

Express Mail Label No.

Dated: _____

Docket No.: 20099/0200781-USO
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Ken Koyama et al.

Application No.: 10/781,358

Confirmation No.: 9212

Filed: February 17, 2004

Art Unit: 1775

For: Al-Cu BONDED STRUCTURE AND METHOD
FOR MAKING THE SAME

Examiner: John J. Zimmerman

**DISCLAIMING DECLARATION OF
KENJI IKEDA UNDER 37 C.F.R. § 1.132**

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

I, Kenji IKEDA, do hereby declare and state as follows:

1. I am a citizen of Japan and am more than twenty-one years of age.
2. Ken Koyama, Keiji Miki, Atsushi Mochida, Kenji Ikeda, Makoto Yoshida, and Kenji Shinozaki, and myself are co-authors of the article entitled "Improvement of Strength of Brazing Joint using Ag as Insert Metal - Development of Brazing Technique for Al-Cu Dissimilar Joint (Part 2)," *Light Metal Soldering*, Vol. 41 (2003) No. 2, pages 29-82 (hereinafter "Article"). Upon information and belief, this article was published on February 16, 2003, *i.e.*, less than one year prior to the international filing date (August 13, 2003) of the PCT application. The present application is a national stage of the PCT application indicated above.

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7. I further declare that all statements herein of my knowledge are true and that all statements made on information and belief are believed to be true; and further that willful false statements and the like so made are punishable by fine or imprisonment, or both, under §1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the present application or any patent issuing thereon.

Dated: December 4, 2004

Kenji Ikeda
Kenji Ikeda